

Title (en)  
INKJET HEAD AND INKJET HEAD MANUFACTURING METHOD

Title (de)  
TINTENSTRAHLKOPF UND TINTENSTRAHLKOPFHERSTELLUNGSVERFAHREN

Title (fr)  
TÊTE À JET D'ENCRE, ET PROCÉDÉ DE FABRICATION DE TÊTE À JET D'ENCRE

Publication  
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Application  
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Abstract (en)  
[origin: EP3199351A1] The present invention addresses the problem of providing an inkjet head with which reliable electrical connections are possible as a result of a simple and novel configuration for making the heights of contact surfaces of electrodes on a head chip and wiring on a circuit board equal, and a manufacturing method for said inkjet head. The problem is solved by: a head chip (10) having a lead part (153) drawn to the outside of a piezoelectric element (15), on the upper surface of which a first electrode section (151) is formed and on the lower surface of which a second electrode section (152) is formed, the lead part being drawn from the second electrode section (152) of the piezoelectric element (15); a circuit board (20), which is disposed above the head chip (10), having a first connection member (25) obtained from a stud bump that is to be connected to the first electrode section (151) and a second connection member (26) obtained from a stud bump that is to be connected to the second electrode section (152) via the lead part (153); the lead part (153) being provided with an adjusting member (16), the upper surface of which is roughly the same height as the height of the first electrode section (151) and has electrical continuity with the lead part (153); and the first connection member (25) of the circuit board (20) being electrically connected to the upper surface of the first electrode section (151) and the second connection member (26) contacting the upper surface of the adjusting member (16) and being electrically connected to the second electrode section (152) via the adjusting member (16) and the lead part (153).

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